

UTC UNISONIC TECHNOLOGIES CO., LTD

1N50-MS **Power MOSFET Preliminary**

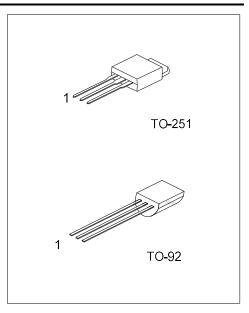
1A, 500V N-CHANNEL **POWER MOSFET**

DESCRIPTION

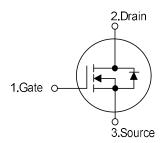
The UTC 1N50-MS is a high voltage power MOSFET designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and high rugged avalanche characteristics. This power MOSFET is usually used in high speed switching applications of switching power supplies and adaptors.

FEATURES

- * $R_{DS(ON)} \le 8.5 \Omega$ @ $V_{GS}=10V$, $I_D=0.5A$
- * Fast switching capability
- * Avalanche energy tested
- * Improved dv/dt capability, high ruggedness



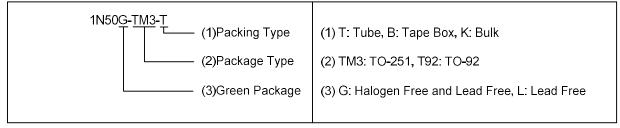
SYMBOL



ORDERING INFORMATION

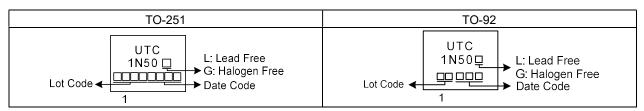
Ordering Number		Dookogo	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
1N50L-TM3-T	1N50G-TM3-T	TO-251	G	D	S	Tube	
1N50L-T92-B	1N50G-T92-B	TO-92	G	D	S	Tape Box	
1N50L-T92-K	1N50G-T92-K	TO-92	G	D	S	Bulk	

Note: Pin Assignment: G: Gate D: Drain S: Source



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■ MARKING



■ **ABSOLUTE MAXIMUM RATINGS** (T_C = 25°C, unless otherwise specified)

PARAMETER		SYMBOL RATINGS		UNIT	
Drain-Source Voltage		V_{DSS}	500	V	
Gate-Source Voltage		V_{GSS}	±30	V	
Continuous Drain Current		I _D	1	Α	
Pulsed Drain Current (Note 2)		I _{DM}	2	Α	
Avalanche Energy	Single Pulsed (Note 3)	E _{AS}	38	mJ	
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.5	V/ns	
Power Dissipation	TO-251	-	25	W	
	TO-92	P_D	2.7	W	
Junction Temperature		TJ	+150	°C	
Storage Temperature		T _{STG}	-55 ~ +150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 30mH, I_{AS} = 1.6A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25°C
- 4. $I_{SD} \le 1.0$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25$ °C

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-251	0	110	°C/W
	TO-92	θ _{JA}	160 (Note)	°C/W
Junction to Case	TO-251	0	5 (Note)	°C/W
	TO-92	θ _{JC}	45 (Note)	°C/W

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

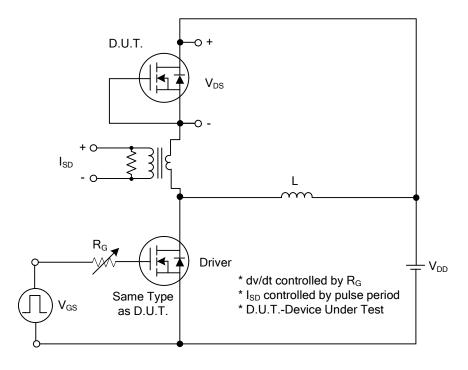
■ **ELECTRICAL CHARACTERISTICS** (T_J =25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS		•			•				
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} =0V, I _D =250μA	500			V		
Drain-Source Leakage Current		I _{DSS}	V _{DS} =500V, V _{GS} =0V			10	μA		
Gate- Source Leakage Current	Forward] ,	V _{GS} =30V, V _{DS} =0V			100	nA		
	Reverse	I_{GSS}	V _{GS} =-30V, V _{DS} =0V			-100	nA		
ON CHARACTERISTICS									
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=250\mu A$	2.0		4.0	V		
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =0.5A			8.5	Ω		
DYNAMIC CHARACTERISTICS									
Input Capacitance	nput Capacitance				86		pF		
Output Capacitance		Coss	V _{DS} =25V, V _{GS} =0V, f=1.0MHz		18		pF		
Reverse Transfer Capacitance		C _{RSS}			2		pF		
SWITCHING CHARACTERISTICS									
Total Gate Charge (Note 1)		Q_G	V _{DS} =400V, V _{GS} =10V, I _D =1A		3.6		nC		
Gate-Source Charge		Q_GS	I_{G} =1mA (Note 1, 2)		1.8		nC		
Gate-Drain Charge		Q_{GD}	IG-IIIA (Note 1, 2)		0.4		nC		
Turn-On Delay Time (Note 1)		t _{D(ON)}			3		ns		
Turn-On Rise Time		t _R	V _{DS} =100V, V _{GS} =10V, I _D =1A,		16		ns		
Turn-Off Delay Time		t _{D(OFF)}	R _G =25Ω (Note 1, 2)		11		ns		
Turn-Off Fall Time		t _F			29		ns		
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS									
Maximum Body-Diode Continuous Current		Is				1	Α		
Maximum Body-Diode Pulsed Current		I _{SM}				2	Α		
Drain-Source Diode Forward Voltage (Note 1)		V_{SD}	I _S =1A , V _{GS} =0V			1.4	V		
Reverse Recovery Time (Note 1)		t _{rr}	I _S =1A , V _{GS} =0V		145		ns		
Reverse Recovery Charge		Qrr	di/dt=100A/µs		0.86		μC		

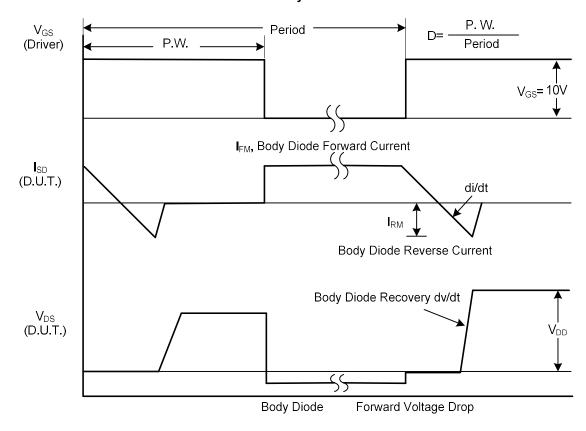
Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2%.

^{2.} Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS

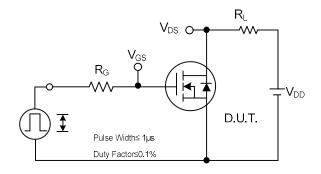


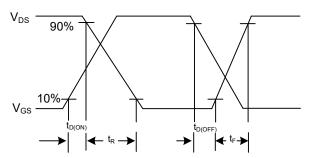
Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

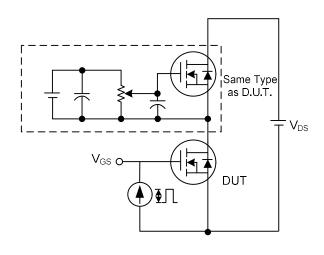
■ TEST CIRCUITS AND WAVEFORMS

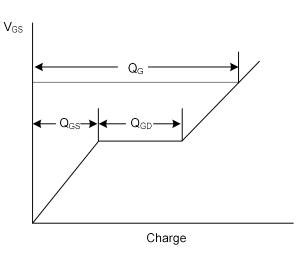




Switching Test Circuit

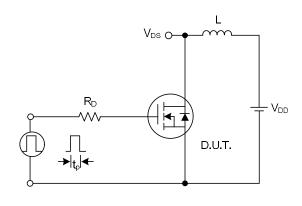
Switching Waveforms

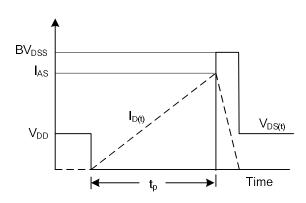




Gate Charge Test Circuit

Gate Charge Waveform





Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

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